

Modular Building Blocks

Infinite Possibility Awaits



Modular Design to Create Multiple Systems

Ingrasys develops a game-changing approach to break down the legacy servers into reusable modular components, and mix and match them to build up multiple new systems. This approach creates unlimited possibilities and allows for future scalability across different generations of platforms.

One Module, Maximum Flexibility

Reuse the modules as much as possible. When the system needs to be updated, only replace one module with a new one with no other changes required.

Support Enterprise EIA 19" and ORv3 Racks

Use the same modular components differently to configure systems respectively for Enterprise EIA 19" rack and Open Compute ORv3 rack.

Rack-integrated Liquid Cooling Solution

Ingrasys OCP-compliant server supports liquid cooling technology to provide higher cooling efficiency, which allows high-power CPU and GPU to run at their full performance while reducing significant energy consumption.



Truly Flexible Systems



Customized Modules



Faster Time-to-Market Solution



Easy Future Scalability



Air & Liquid Cooling Solutions

Modular Building Blocks

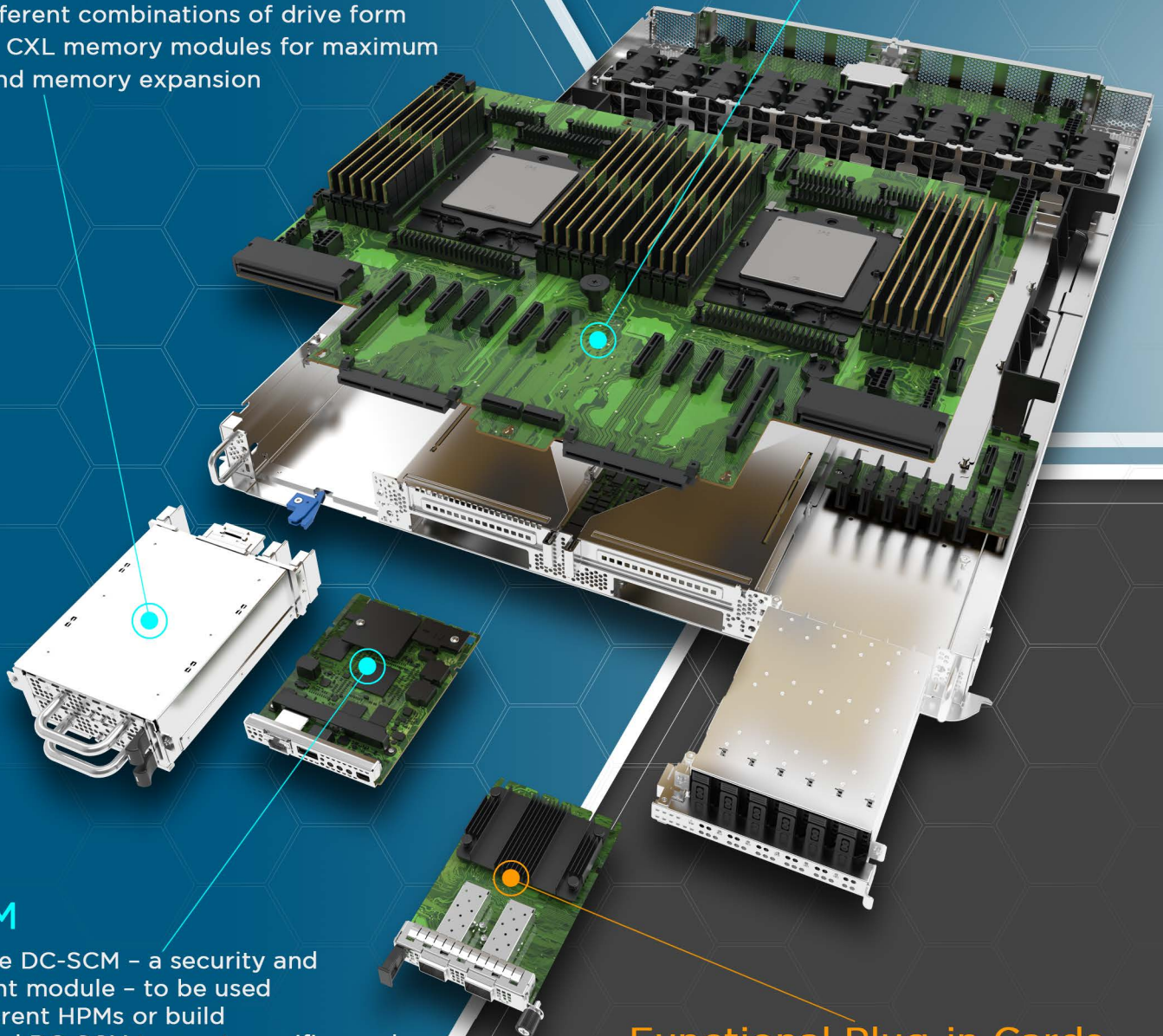
Modules

HPM

Develop one HPM for each CPU family to simply hardware design to a minimum extent

Drive Cages & Interposers

Support different combinations of drive form factors and CXL memory modules for maximum flexibility and memory expansion



DC-SCM

Develop one DC-SCM – a security and management module – to be used across different HPMs or build a customized DC-SCM to meet specific needs

Functional Plug-in Cards

Install PCIe CEM card modules and OCP NIC to realize different high-speed I/O functions



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SV1120A

Specifications



North America: +1 408-727-8060



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HPM/Motherboard

AMD Platform



Processor

2 x 4th Gen AMD EPYC™ Processors



Memory

24 x DDR5 RDIMMs, 12-Channel per CPU,
up to 4800 MT/s at 1DPC



Storage

- **SKU 1:** 24 x E1.S SSDs,
2 x 22110 M.2 Boot Drives
- **SKU 2:** 12 x U.2 NVMe SSDs,
2 x 22110 M.2 Boot Drives



I/O Ports

- 1 x 1GbE/RJ45 Management Port
- 1 x USB 2.0
- 1 x Mini Display Port
- 1 x Reset Button
- 1 x Power Button with LED
- 1 x UID Button with LED



Form Factor

1 RU



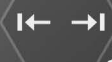
Expansion Slots

2 x PCIe 5.0 x16 FHHL Slots
1 x PCIe 5.0 x16 OCP NIC 3.0



Power Supply

2 x 2400W Platinum
Redundant (1+1) PSU



Chassis Dimensions (H x W x D)

1.71" x 17.32" x 32.4" /
43.4mm x 440.0mm x 823.4mm



Security & Management

DC-SCM 1.0 (Root of Trust, TPM,
AST2600 BMC)



Cooling Solution

8 x 4056 Dual Rotor System Fans
(N+1 Redundant)



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Specifications



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HPM/Motherboard

Intel Platform



Processor

2 x 4th Gen Intel® Xeon® Scalable Processors



Memory

32 x DDR5 RDIMMs, 8-Channel per CPU,
up to 4800 MT/s at 1DPC, 4400 MT/s at 2DPC



Storage

- **SKU 1:** 24 x E1.S SSDs,
2 x 22110 M.2 Boot Drives
- **SKU 2:** 12 x U.2 NVMe SSDs,
2 x 22110 M.2 Boot Drives



I/O Ports

- 1 x 1GbE/RJ45 Management Port
- 1 x USB 2.0
- 1 x Mini Display Port
- 1 x Reset Button
- 1 x Power Button with LED
- 1 x UID Button with LED



Form Factor

1 RU



Expansion Slots

2 x PCIe 5.0 x16 FHHL Slots
1 x PCIe 5.0 x16 OCP NIC 3.0



Power Supply

2 x 2400W Platinum
Redundant (1+1) PSU



Chassis Dimensions (H x W x D)

1.71" x 17.32" x 32.4" /
43.4mm x 440.0mm x 823.4mm



Security & Management

DC-SCM 1.0 (Root of Trust, TPM,
AST2600 BMC)



Cooling Solution

8 x 4056 Dual Rotor System Fans
(N+1 Redundant), CPU Remote Heatsink



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Specifications



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HPM/Motherboard

AMD Platform



Processor

2 x 4th Gen AMD EPYC™ Processors



Memory

- 24 x DDR5 RDIMMs, 12-Channel per CPU, up to 4800 MT/s at 1DPC
- 2 x E3.S CXL Memory Modules (SKU 3)



Storage

- **SKU 1:** 12 x E1.S SSDs
- **SKU 2:** 6 x E1.S SSDs
- **SKU 3:** 6 x E1.S SSDs
- All SKUs with 2 x 22110 M.2 Boot Drives



Expansion Slots

- **SKU 1 & 3:** 2 x PCIe 5.0 x16 FHHL Slots
1 x PCIe 5.0 x16 OCP NIC 3.0
- **SKU 2:** 2 x PCIe 5.0 x16 FHHL Slots
2 x PCIe 5.0 x16 LP/HHHL with Riser Card Slots
1 x PCIe 5.0 x16 OCP NIC 3.0



Form Factor

1 OU



I/O Ports

- 1 x 1GbE/RJ45 Management Port
- 1 x USB 2.0
- 1 x Mini Display Port
- 1 x Reset Button
- 1 x Power Button with LED
- 1 x UID Button with LED



Power Supply

Centralized 48V Bus Bar with PDB



Chassis Dimensions (H x W x D)

1.75" x 21.14" x 31.76" /
44.7mm x 537.0mm x 806.7mm



Security & Management

DC-SCM 1.0 (Root of Trust, TPM, AST2600 BMC)



Cooling Solution

- **Air:** CPU Remote Heatsink, 11 x 4056 Dual Rotor System Fans (N+1 Redundant)
- **Liquid:** CPU Cold-Plates to Rack Quick-Disconnects, 7 x 4056 Dual Rotor System Fans (N+1 Redundant)



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Specifications



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HPM/Motherboard

Intel Platform



Processor

2 x 4th Gen Intel® Xeon® Scalable Processors



Memory

- 32 x DDR5 RDIMMs, 8-Channel per CPU, up to 4800 MT/s at 1DPC, 4400 MT/s at 2DPC
- 2 x E3.S CXL Memory Modules (SKU 3)



Storage

- **SKU 1:** 12 x E1.S SSDs
- **SKU 2:** 6 x E1.S SSDs
- **SKU 3:** 6 x E1.S SSDs
- All SKUs with 2 x 22110 M.2 Boot Drives



Expansion Slots

- **SKU 1 & 3:** 2 x PCIe 5.0 x16 FHHL Slots
1 x PCIe 5.0 x16 OCP NIC 3.0
- **SKU 2:** 2 x PCIe 5.0 x16 FHHL Slots
2 x PCIe 5.0 x16 LP/HHHL with Riser Card Slots
1 x PCIe 5.0 x16 OCP NIC 3.0



Form Factor

1 OU



I/O Ports

- 1 x 1GbE/RJ45 Management Port
- 1 x USB 2.0
- 1 x Mini Display Port
- 1 x Reset Button
- 1 x Power Button with LED
- 1 x UID Button with LED



Power Supply

Centralized 48V Bus Bar with PDB



Chassis Dimensions (H x W x D)

1.75" x 21.14" x 31.76" /
44.7mm x 537.0mm x 806.7mm



Security & Management

DC-SCM 1.0 (Root of Trust, TPM, AST2600 BMC)



Cooling Solution

- **Air:** CPU Remote Heatsink, 11 x 4056 Dual Rotor System Fans (N+1 Redundant)
- **Liquid:** CPU Cold-Plates to Rack Quick-Disconnects, 7 x 4056 Dual Rotor System Fans (N+1 Redundant)



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Specifications



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HPM/Motherboard

AMD Platform



Processor

2 x 4th Gen AMD EPYC™ Processors



Memory

24 x DDR5 RDIMMs, 12-Channel per CPU,
up to 4800 MT/s at 1DPC



I/O Ports

1 x 1GbE/RJ45 Management Port
1 x USB 2.0
1 x Mini Display Port
1 x Reset Button
1 x Power Button with LED
1 x UID Button with LED



Form Factor

2 OU



Expansion Slots

2 x PCIe 5.0 x16 FHHL Slots
8 x PCIe 5.0 x16 LP/HHHL with Riser
Card Slots



Power Supply

Centralized 48V Bus Bar
with PDB



Chassis Dimensions (H x W x D)

3.68" x 21.14" x 31.76" /
93.5mm x 537.0mm x 806.7mm



Security & Management

DC-SCM 1.0 (Root of Trust, TPM,
AST2600 BMC)



Cooling Solution

- **Air:** CPU Remote Heatsink, 5 x 8056 Dual Rotor System Fans (N+1 Redundant)
- **Liquid:** CPU Cold-Plates to Rack Quick-Disconnects, 4 x 8056 Dual Rotor System Fans (N+1 Redundant)



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HPM/Motherboard

Intel Platform



Processor

2 x 4th Gen Intel® Xeon® Scalable Processors



Memory

32 x DDR5 RDIMMs, 8-Channel per CPU,
up to 4800 MT/s at 1DPC, 4400 MT/s at 2DPC



I/O Ports

1 x 1GbE/RJ45 Management Port
1 x USB 2.0
1 x Mini Display Port
1 x Reset Button
1 x Power Button with LED
1 x UID Button with LED



Form Factor

2 OU



Expansion Slots

2 x PCIe 5.0 x16 FHHL Slots
8 x PCIe 5.0 x16 LP/HHHL with Riser
Card Slots



Power Supply

Centralized 48V Bus Bar
with PDB



Chassis Dimensions (H x W x D)

3.68" x 21.14" x 31.76" /
93.5mm x 537.0mm x 806.7mm



Security & Management

DC-SCM 1.0 (Root of Trust, TPM,
AST2600 BMC)



Cooling Solution

- **Air:** CPU Remote Heatsink, 5 x 8056 Dual Rotor System Fans (N+1 Redundant)
- **Liquid:** CPU Cold-Plates to Rack Quick-Disconnects, 4 x 8056 Dual Rotor System Fans (N+1 Redundant)



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